





Integrated Device Technology, Inc.  
6024 Silver Creek Valley Road, San Jose, CA - 95138

## PRODUCT/PROCESS CHANGE NOTICE (PCN)

### ATTACHMENT I - PCN #: TB1507-01

**PCN Type:** Change in Moisture Sensitivity Level

**Data Sheet Change:** There is change in Moisture Sensitive Level (MSL) from 3 to 1.

**Detail of Change:** This notification is to advise our customers that IDT is converting moisture sensitivity classification to MSL 1.

The affected products will be shipped without dry pack and labeled as MSL 1 according to JEDEC J-STD-020. There is no change to the assembly material sets and the peak reflow temperature. Peak reflow temperature remains 260°C.

Refer to examples of moisture sensitive labels as shown below.

#### Qualification Information and Qualification Data:

**Qual Plan & Results:** Tests are in accordance with JEDEC47 recommended tests.

**Qualification Vehicle:** VFQFPN-16

Test Description	Test Method	Test Results (SS / Rej)		
		Lot 1	Lot 2	Lot 3
* HAST - biased (130 °C/85% RH, 100 Hrs)	JESD22-A110	45/0	45/0	45/0
* Temperature Cycle / Condition B (-55 °C to +125 °C, 700 Cyc)	JESD22-A104	45/0	45/0	45/0
High Temp. Storage Test (150 °C, 1000 Hrs)	JESD22-A103	77/0	77/0	77/0
Moisture Sensitivity Level (MSL 1, 260°C)	J-STD-20	45/0	45/0	45/0

\* Test requires moisture pre-conditioning sequence per JESD22-A113 prior to stress test

#### From: MSL 3 Moisture Sensitive Label



**CAUTION**  
This Bag Contains  
**MOISTURE-SENSITIVE DEVICES**

LEVEL  
**3**

1. Calculated shelf life in sealed bag:  
12 months at < 40°C and < 90% relative humidity (RH)
2. Peak package body temperature: 260°C
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must
  - a) Mounted within 168 hours of factory conditions <= 30°C/60% RH
  - b) Stored per J-STD-033
4. Devices required bake, before mounting if:
  - a) Humidity indicator card reads >10% for level 2a-5a devices or >60% for level 2 devices when read at 23 +/-5 deg C
  - b) 3a or 3b are not met
5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure **Bag Seal Date: 07/31/15**

Note: Level and body temperature defined by IPC/JEDEC J-STD-020.



#### To: MSL 1 Non-Moisture Sensitive Label


**NOT MOISTURE SENSITIVE**

LEVEL  
**1**

These Devices do not require special storage conditions provided:

1. They are maintained at conditions equal to or less than 30°C/85 % RH, and
2. They are solder reflowed at a peak body temperature which does not exceed 260°C

Note: Level and body temperature defined by IPC/JEDEC J-STD-020.



**Note: There is no change to the peak reflow temperature of the affected products.**



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### ATTACHMENT II - PCN #: TB1507-01

#### Affected Part Numbers

Part Number	Part Number	Part Number	Part Number
F2250NLGI	F2258NLGI	F2255NLGI8	F2250NLGK
F2258NLGK	F2255NLGK8	F2255NLGI	F2250NLGI8
F2258NLGI8	F2255NLGK	F2250NLGK8	F2258NLGK8